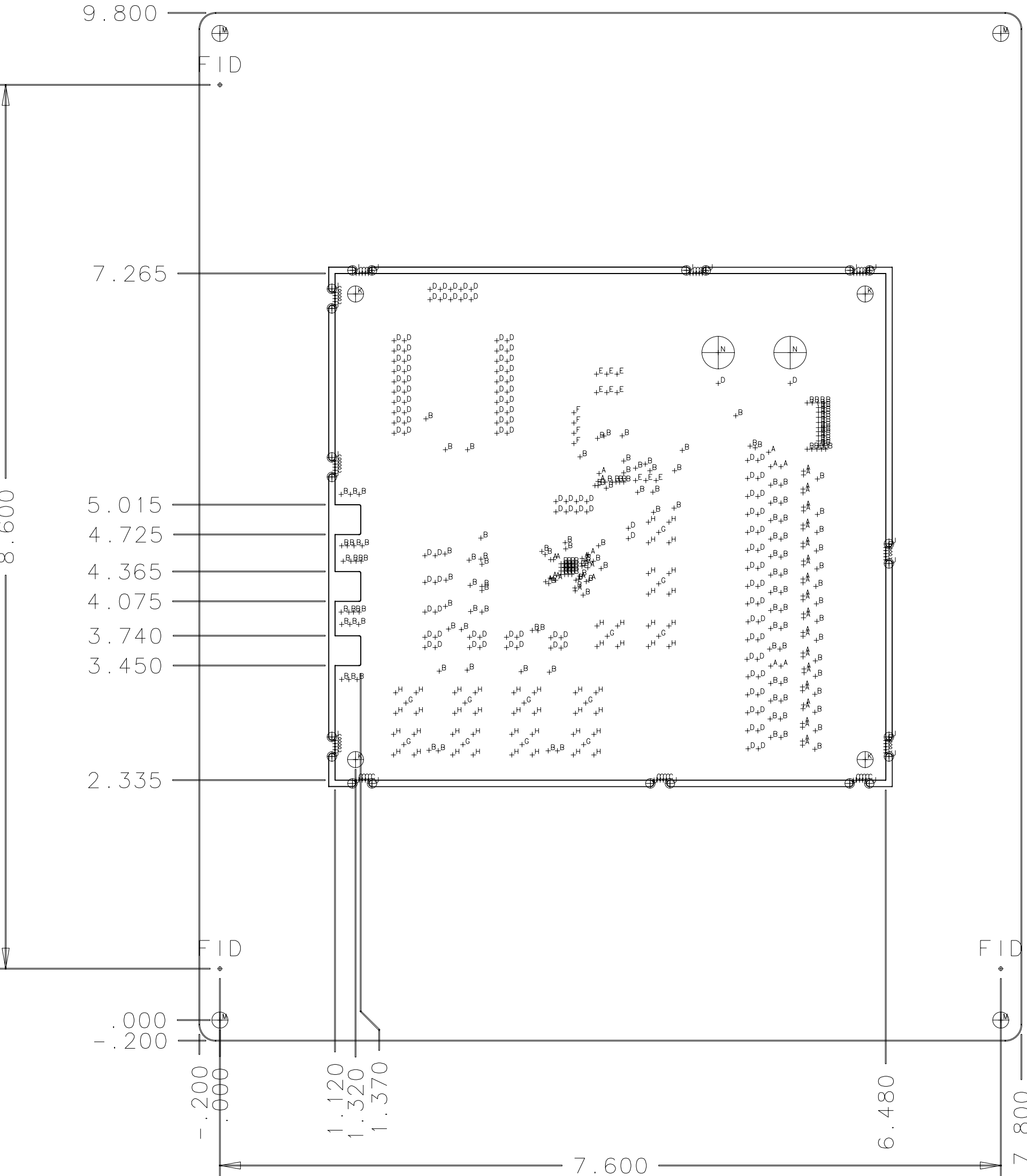


D

C

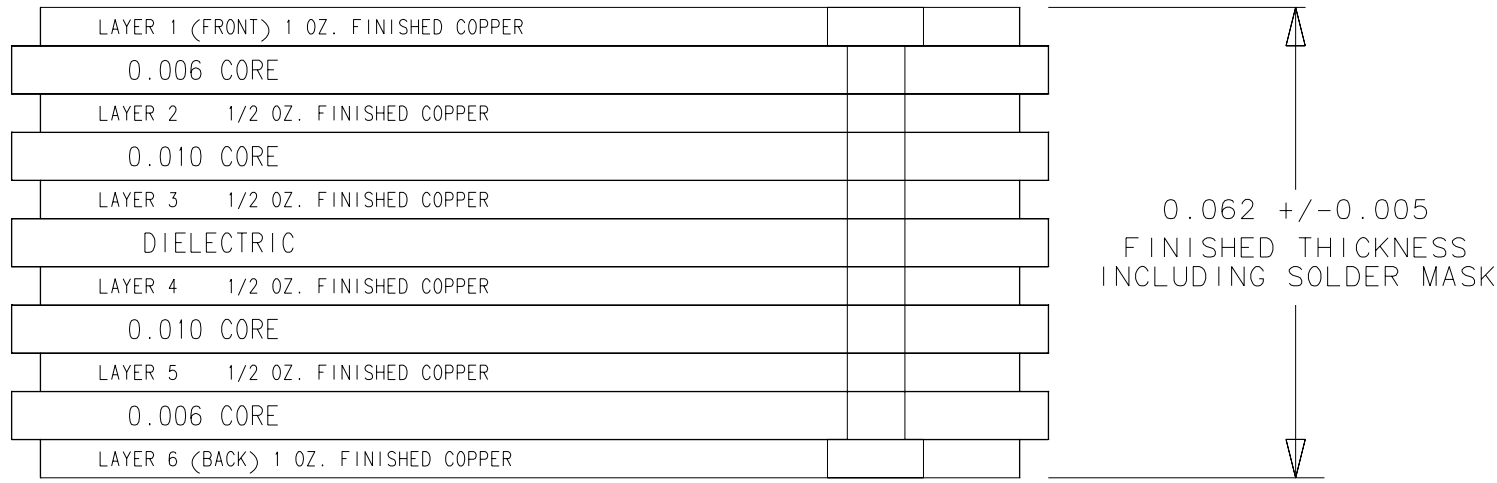
B

A



PANEL 's HOLE SCHEDULE

DRILL SYMBOL	FINISHED HOLE SIZE	COUNT	TYPE	Min/Max
+ <sup>A</sup>	0.006	54	VIA	+0.002 -0.006
+ <sup>B</sup>	0.008	174	VIA	+0.002 -0.008
+ <sup>C</sup>	0.015	55	NPTH	+/-0.003
+ <sup>D</sup>	0.040	118	PTH	+/-0.003
+ <sup>E</sup>	0.042	9	PTH	+/-0.003
+ <sup>F</sup>	0.047	4	PTH	+/-0.003
+ <sup>G</sup>	0.062	12	PTH	+/-0.003
+ <sup>H</sup>	0.067	48	PTH	+/-0.003
+ <sup>J</sup>	0.094	22	NPTH	+/-0.003
+ <sup>K</sup>	0.158	4	NPTH	+/-0.003
+ <sup>M</sup>	0.159	4	NPTH	+/-0.001
+ <sup>N</sup>	0.320	2	NPTH	+/-0.003



CROSS SECTION DETAIL

NOT DRAWN TO SCALE  
(FOR REFERENCE ONLY)

CONTROLLED IMPEDANCE TABLE

TYPE OF FEATURE	NOMINAL LINE WIDTH	PHYSICAL LAYERS	GND REF LAYERS	IMPEDANCE IN OHMS
MICROSTRIP	0.0105"	1	2 GND AREA	50 OHM
MICROSTRIP	0.006"	1	3 GND	100 OHM
MICROSTRIP	0.030"	1	3 GND	50 OHM

PART NUMBER	REV	DATE CODE	CIRCUITRY		SOLDER MASK		SILKSCREEN		GOLD MASK		OUTLINE		INNER LAYER							
			FRONT	BACK	FRONT	BACK	FRONT	BACK	FRONT	BACK	BOARD	PANEL	1	2	3	4	5	6	7	8
1395-407-84	A	050109	X	X	X	X	X					X	X	X	X					

		± .XX ± 0.01 ± ± .XXX ± 0.005	APPROVALS		DATE		PCB - SIREN C DRILL DRAWING			
		MATERIAL SEE NOTE 2	DRAWN DGC		5/01/09					
1395-307A	RFIC	FINISH SEE NOTE 7	CHECKED							
NEXT ASSY	USED ON		ISSUED							
APPLICATION		DO NOT SCALE DRAWING	MENTOR		SIZE D	FSCM NO.	DWG. NO. 1395-407-84A	REV. A		
					SCALE 1:1			SHEET 1 OF 1		

DWG. NO.		1395-407-84A		SH	REV	A	1	
REVISIONS								
ZONE	REV.	DESCRIPTION					DATE	APPROVED
	A	INITIAL RELEASE					5/1/09	DGC

- NOTES:
- REFER TO SPECIFICATION # 1343A703, "PRINTED CIRCUIT BOARD MATERIAL SPECIFICATION, VERSION 2.4" FOR FABRICATION AND INSPECTION REQUIREMENTS.
  - MATERIAL: USE LAMINATE AND PREPREG PER IPC-4101:  
☐ FR4 ( /21 ), ☐ POLYIMIDE ( /40 ), ☐ BT EPOXY ( /30 );  
☒ HIGH TEMP FR4 ( /24 ), ☐ \_\_\_\_\_ :  
☐ SINGLE SIDED, ☐ DOUBLE SIDED, ☒ MULTILAYER 6 LAYERS;  
☐ DIELECTRIC CONSTANT \_\_\_\_\_  
☐ HDI: \_\_\_\_\_ CONSTRUCTION.
  - FINISHED COPPER THICKNESS SHALL BE:  
☒ 0.0005-0.0010 (APPROX. 1/2 OZ) ☒ INTERNAL;  
☒ 0.0012-0.0019 (APPROX. 1 OZ) ☒ EXTERNAL, ☐ INTERNAL;  
☐ 0.0023-0.0033 (APPROX. 2 OZ) ☐ EXTERNAL, ☐ INTERNAL  
COPPER PLATING IN PLATED HOLES TO BE PER IPC-6012, CLASS 3.  
☐ COPLANAR COPPER THICKNESS ON THE OUTER LAYERS.
  - BOARD THICKNESS SHALL BE 0.062 +/-0.005  
☒ FINISHED BOARD, ☐ LAMINATE.  
SEE CROSS SECTION DETAIL FOR MULTILAYER BOARDS.
  - TECHNOLOGY:  
MINIMUM LINE/SPACE USED: 0.005 /0.005 ;  
MINIMUM COMPONENT PITCH: 0.020  
☒ CONTROLLED IMPEDANCE.
  - ☒ SOLDER MASK: APPLY PHOTO-IMAGEABLE: ☒ WET FILM (LPI),  
☐ DRY FILM SOLDER MASK OVER BARE COPPER, UNLESS GOLD IS USED AS AN ETCH MASK, TO: ☐ FRONT, ☐ BACK, ☒ BOTH SIDE(S) USING ARTWORK SUPPLIED.  
COLOR TO BE: ☐ GREEN, ☐ RED, ☒ MAGENTA  
☐ VIAS TO BE PLUGGED WITH SOLDER MASK FROM: ☐ FRONT, ☐ BACK SIDE FOR THE: ☐ ENTIRE BOARD, ☐ AREA INDICATED.
  - FINISH/PLATING:  
☐ HASL - AREAS EXPOSED BY SOLDER MASK TO BE HOT AIR SOLDER LEVELED 0.000300 - 0.003000 THICK.  
☒ ENIG - AREAS EXPOSED BY SOLDER MASK TO BE IMMERSION GOLD PLATED 0.00000118 - 0.00000394 THICK OVER ELECTROLESS NICKEL 0.000118 - 0.000300 THICK.  
☐ ALL CONDUCTIVE PATTERNS TO BE PLATED 0.000118 - 0.000300 THICK OF NICKEL. GOLD PLATE WITH SOFT/WIREBONDABLE GOLD 0.000040 - 0.000060 THICK.  
☐ CONDUCTORS TO BE PLATED 0.000118 - 0.000300 THICK OF NICKEL. HARD GOLD PLATE 0.000060 THICK MINIMUM ☐ WHERE SPECIFIED, USING ARTWORKS SUPPLIED, ☐ ALL CONDUCTORS.  
☐ ENEG - AREAS EXPOSED BY SOLDER MASK TO BE ELECTROLESS GOLD PLATED 0.000020 - 0.000040 THICK OVER ELECTROLESS NICKEL 0.000118 - 0.000300 THICK.  
☐ OSP - CLEAR ORGANIC BASED COATING (ENTEK CU-106A).  
☐ PTF RESISTORS ON LAYER \_\_\_\_\_, USING INK(S) \_\_\_\_\_  
☐
  - ☒ LEGEND/SILKSCREEN ON THE ☒ FRONT, ☐ BACK, ☐ BOTH SIDE(S). USE NON-CONDUCTIVE, EPOXY INK, COLOR WHITE.
  - ☒ PANELIZED: 1 BOARDS PER PANEL.
  - CERTIFICATIONS/REPORTS:  
☒ IPC-6012, CLASS 3 CERTIFICATION  
☒ CROSS-SECTION REPORT  
☒ NETLIST ELECTRICAL TEST TO BE PERFORMED AS THE FINAL STEP. TEST 100% FOR OPENS AND SHORTS PER THE FOLLOWING:  
☐ SINGLE SIDE ACCESS  
☒ DUAL SIDE ACCESS  
☐ PLATING COMPOSITION AND THICKNESS CERTIFICATION  
☐ WIREBOND TEST COUPON REQUIRED FOR EACH PANEL.
  - ☐ BOARD CONSTRUCTION TO BE THE SAME AS: ☐ THE LAST REVISION OF THIS PART, ☐ \_\_\_\_\_. PLEASE REFER TO PREVIOUS BUILD INFORMATION.
  - ☒ CRITICAL FEATURES: 100% INSPECTION REQUIRED OF FEATURES INDICATED IN TABLE.